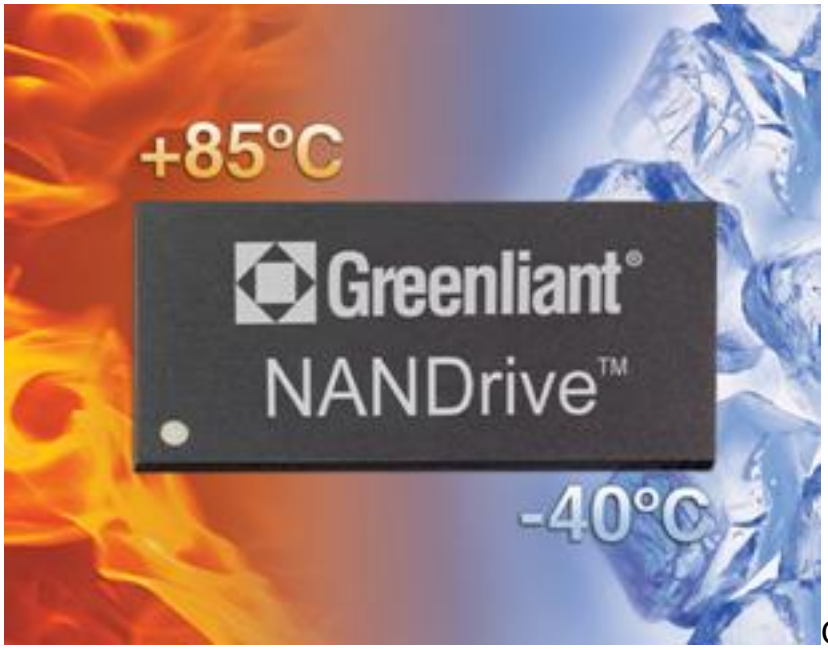
SSD in multi-chip package offers flexibility, choices



Greenliant Systems is now sampling its industrial temperature SATA and PATA interface NANDrive embedded solid state drives (SSDs) using 2-bits-per-cell (MLC) NAND flash memory. The new NANDrive devices are the first ball grid array (BGA) package SATA / PATA SSDs based on MLC NAND that are capable of operating at temperatures between -40 to +85 degrees Celsius.

NANDrive combines Greenliant's internally developed NAND controller with NAND flash die for a fully integrated SSD in a multi-chip package. SATA and PATA NANDrive products have the same pin-out across all capacities in each family to ensure backward compatibility and simplify board design. The BGA package allows for easy and firm mounting to a system motherboard, and the 1mm ball pitch increases long-term reliability for applications enduring mechanical shock, vibration and temperature cycling.

The addition of MLC NAND-based industrial temperature NANDrive devices builds on Greenliant's high-endurance industrial grade product offerings, giving customers more choices and flexibility when selecting embedded SSDs to meet their design needs.

Availability
Greenliant is currently sampling industrial temperature GLS85LS SATA and GLS85LP PATA NANDrive devices in 8, 16, 32 and 64 GByte with customers on select product engagements. For more information about the Greenliant NANDrive product portfolio, visit www.NANDrive.com and contact a Greenliant authorized distributor or sales representative.

NANDrive
www.NANDrive.com [1]

Greenliant Systems
www.greenliant.com [2]

Source URL (retrieved on *09/16/2014 - 4:27am*):
http://www.ecnmag.com/products/2012/08/ssd-multi-chip-package-offers-flexibility-choices

Links:
[1] http://%20www.NANDrive.com
[2] http://www.greenliant.com